



**THE DATASHEET OF  
IPAN60R800CEXKSA1**



## MOSFET

### 600V CoolMOS™ CE Power Transistor

CoolMOS™ is a revolutionary technology for high voltage power MOSFETs, designed according to the superjunction (SJ) principle and pioneered by Infineon Technologies. CoolMOS™ CE is a price-performance optimized platform enabling to target cost sensitive applications in Consumer and Lighting markets by still meeting highest efficiency standards. The new series provides all benefits of a fast switching Superjunction MOSFET while not sacrificing ease of use and offering the best cost down performance ratio available on the market.

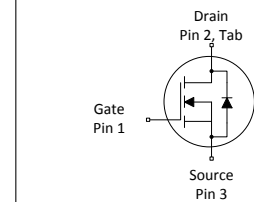
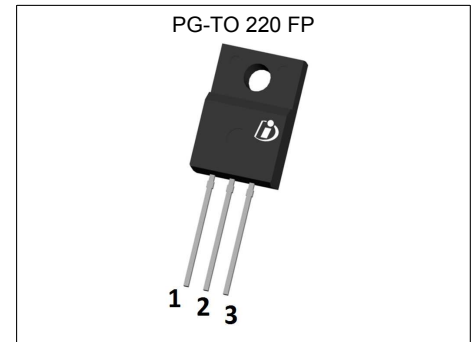
### Features

- Extremely low losses due to very low FOM  $R_{DS(on)} \cdot Q_g$  and  $E_{oss}$
- Very high commutation ruggedness
- Easy to use/drive
- Pb-free plating, Halogen free mold compound
- Qualified for standard grade applications

### Applications

PFC stages, hard switching PWM stages and resonant switching stages for e.g. PC Silverbox, Adapter, LCD & PDP TV and indoor lighting.

*Please note: Note1: For MOSFET paralleling the use of ferrite beads on the gate or separate totem poles is generally recommended.*



**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	650	V
$R_{DS(on),max}$	800	$m\Omega$
$I_d$	8.4	A
$Q_{g,typ}$	17.2	nC
$I_{D,pulse}$	15.7	A
$E_{oss@400V}$	1.6	$\mu J$

Type / Ordering Code	Package	Marking	Related Links
IPAN60R800CE	PG-TO 220 FullPAK - Narrow Lead	60S800CE	see Appendix A

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## 1 Maximum ratings

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$	-	-	8.4 5.3	A	$T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	-	-	15.7	A	$T_C=25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$	-	-	72	mJ	$I_D=1\text{A}$ ; $V_{DD}=50\text{V}$ ; see table 11
Avalanche energy, repetitive	$E_{AR}$	-	-	0.17	mJ	$I_D=1\text{A}$ ; $V_{DD}=50\text{V}$ ; see table 11
Avalanche current, repetitive	$I_{AR}$	-	-	1.0	A	-
MOSFET dv/dt ruggedness	dv/dt	-	-	50	V/ns	$V_{DS}=0\dots480\text{V}$
Gate source voltage (static)	$V_{GS}$	-20	-	20	V	static;
Gate source voltage (dynamic)	$V_{GS}$	-30	-	30	V	AC ( $f>1\text{ Hz}$ )
Power dissipation (Non FullPAK) TO-252	$P_{tot}$	-	-	48	W	$T_C=25^\circ\text{C}$
Storage temperature	$T_{stg}$	-40	-	150	$^\circ\text{C}$	-
Operating junction temperature	$T_j$	-40	-	150	$^\circ\text{C}$	-
Continuous diode forward current	$I_S$	-	-	5.9	A	$T_C=25^\circ\text{C}$
Diode pulse current <sup>2)</sup>	$I_{S,pulse}$	-	-	15.7	A	$T_C=25^\circ\text{C}$
Reverse diode dv/dt <sup>3)</sup>	dv/dt	-	-	15	V/ns	$V_{DS}=0\dots400\text{V}$ , $I_{SD}\leq I_S$ , $T_j=25^\circ\text{C}$ see table 9
Maximum diode commutation speed	di/dt	-	-	500	A/ $\mu\text{s}$	$V_{DS}=0\dots400\text{V}$ , $I_{SD}\leq I_S$ , $T_j=25^\circ\text{C}$ see table 9
Power dissipation (FullPAK) TO-220FP	$P_{tot}$	-	-	27	W	$T_C=25^\circ\text{C}$
Mounting torque (FullPAK) TO-220FP	-	-	-	50	Ncm	M2.5 screws
Insulation withstand voltage for TO-220FP	$V_{ISO}$	-	-	2500	V	$V_{rms}$ , $T_C=25^\circ\text{C}$ , $t=1\text{min}$

## 2 Thermal characteristics

**Table 3 Thermal characteristics (FullPAK) TO-220FP**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	4.6	$^\circ\text{C/W}$	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	80	$^\circ\text{C/W}$	leaded
Soldering temperature, wavesoldering only allowed at leads	$T_{sold}$	-	-	260	$^\circ\text{C}$	1.6mm (0.063 in.) from case for 10s

<sup>1)</sup> Limited by  $T_{j,max}$ . TO220 equivalent, Maximum duty cycle  $D=0.50$

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{j,max}$

<sup>3)</sup> Identical low side and high side switch with identical  $R_\theta$

### 3 Electrical characteristics

at  $T_j=25^\circ\text{C}$ , unless otherwise specified

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	600	-	-	V	$V_{GS}=0\text{V}$ , $I_D=0.25\text{mA}$
Gate threshold voltage	$V_{(GS)th}$	2.5	3.0	3.5	V	$V_{DS}=V_{GS}$ , $I_D=0.17\text{mA}$
Zero gate voltage drain current	$I_{DSS}$	-	-	1	$\mu\text{A}$	$V_{DS}=600$ , $V_{GS}=0\text{V}$ , $T_j=25^\circ\text{C}$ $V_{DS}=600$ , $V_{GS}=0\text{V}$ , $T_j=150^\circ\text{C}$
Gate-source leakage current	$I_{GSS}$	-	-	100	nA	$V_{GS}=20\text{V}$ , $V_{DS}=0\text{V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	0.68	0.80	$\Omega$	$V_{GS}=10\text{V}$ , $I_D=2\text{A}$ , $T_j=25^\circ\text{C}$ $V_{GS}=10\text{V}$ , $I_D=2\text{A}$ , $T_j=150^\circ\text{C}$
Gate resistance	$R_G$	-	11	-	$\Omega$	$f=1\text{MHz}$ , open drain

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$	-	373	-	pF	$V_{GS}=0\text{V}$ , $V_{DS}=100\text{V}$ , $f=1\text{MHz}$
Output capacitance	$C_{oss}$	-	27	-	pF	$V_{GS}=0\text{V}$ , $V_{DS}=100\text{V}$ , $f=1\text{MHz}$
Effective output capacitance, energy related <sup>1)</sup>	$C_{o(er)}$	-	18	-	pF	$V_{GS}=0\text{V}$ , $V_{DS}=0\dots480\text{V}$
Effective output capacitance, time related <sup>2)</sup>	$C_{o(tr)}$	-	74	-	pF	$I_D=\text{constant}$ , $V_{GS}=0\text{V}$ , $V_{DS}=0\dots480\text{V}$
Turn-on delay time	$t_{d(on)}$	-	9	-	ns	$V_{DD}=400\text{V}$ , $V_{GS}=13\text{V}$ , $I_D=2.5\text{A}$ , $R_G=6.8\Omega$ ; see table 10
Rise time	$t_r$	-	7	-	ns	$V_{DD}=400\text{V}$ , $V_{GS}=13\text{V}$ , $I_D=2.5\text{A}$ , $R_G=6.8\Omega$ ; see table 10
Turn-off delay time	$t_{d(off)}$	-	50	-	ns	$V_{DD}=400\text{V}$ , $V_{GS}=13\text{V}$ , $I_D=2.5\text{A}$ , $R_G=6.8\Omega$ ; see table 10
Fall time	$t_f$	-	12	-	ns	$V_{DD}=400\text{V}$ , $V_{GS}=13\text{V}$ , $I_D=2.5\text{A}$ , $R_G=6.8\Omega$ ; see table 10

**Table 6 Gate charge characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{GS}$	-	2	-	nC	$V_{DD}=480\text{V}$ , $I_D=2.5\text{A}$ , $V_{GS}=0$ to $10\text{V}$
Gate to drain charge	$Q_{gd}$	-	8.9	-	nC	$V_{DD}=480\text{V}$ , $I_D=2.5\text{A}$ , $V_{GS}=0$ to $10\text{V}$
Gate charge total	$Q_g$	-	17.2	-	nC	$V_{DD}=480\text{V}$ , $I_D=2.5\text{A}$ , $V_{GS}=0$ to $10\text{V}$
Gate plateau voltage	$V_{\text{plateau}}$	-	5.4	-	V	$V_{DD}=480\text{V}$ , $I_D=2.5\text{A}$ , $V_{GS}=0$ to $10\text{V}$

<sup>1)</sup>  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{(BR)DSS}$

<sup>2)</sup>  $C_{o(tr)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{(BR)DSS}$

**Table 7 Reverse diode characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$	-	0.9	-	V	$V_{GS}=0V, I_F=2.5A, T_j=25^\circ C$
Reverse recovery time	$t_{rr}$	-	250	-	ns	$V_R=400V, I_F=2.5A, di_F/dt=100A/\mu s$ ; see table 9
Reverse recovery charge	$Q_{rr}$	-	1.8	-	$\mu C$	$V_R=400V, I_F=2.5A, di_F/dt=100A/\mu s$ ; see table 9
Peak reverse recovery current	$I_{rrm}$	-	16	-	A	$V_R=400V, I_F=2.5A, di_F/dt=100A/\mu s$ ; see table 9

### 4 Electrical characteristics diagrams

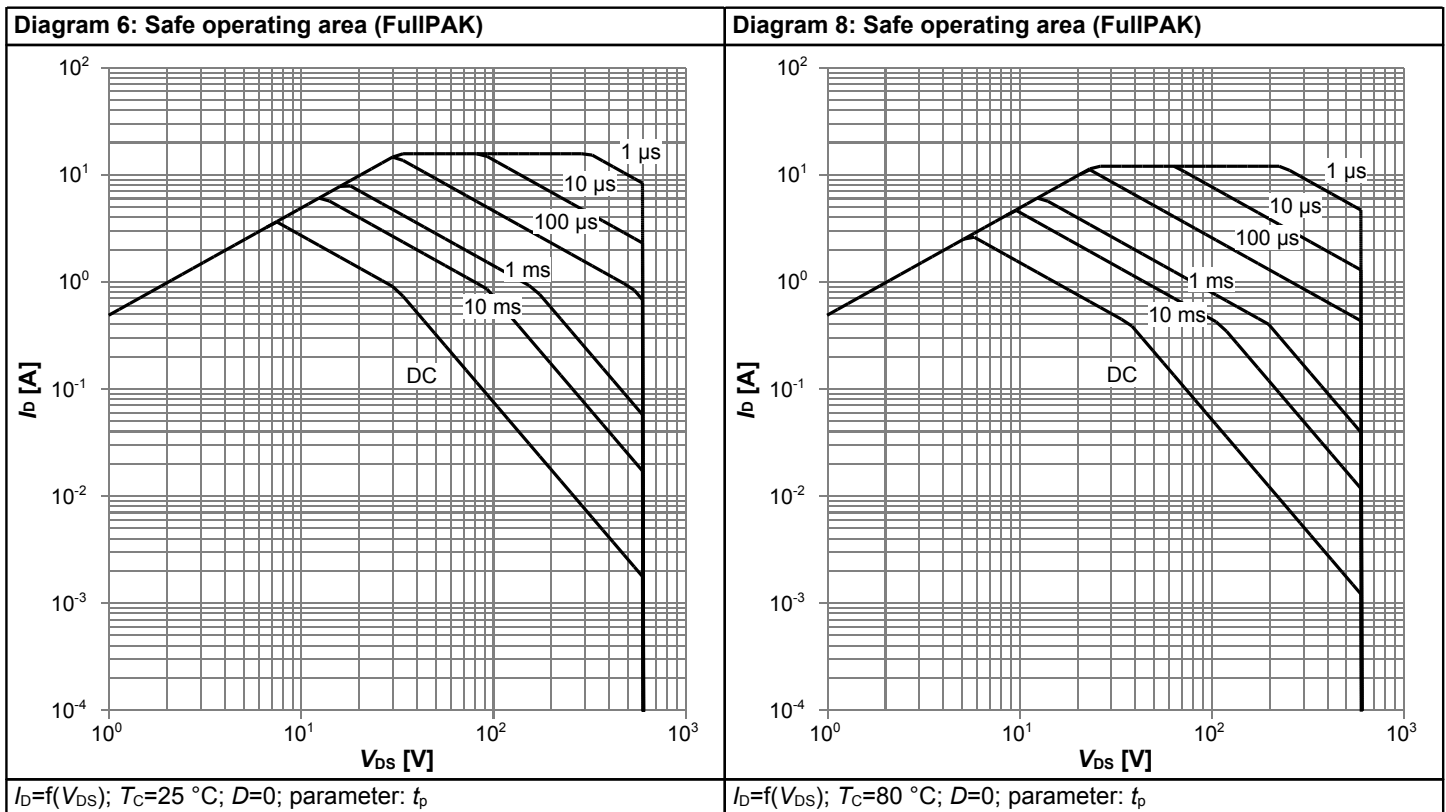
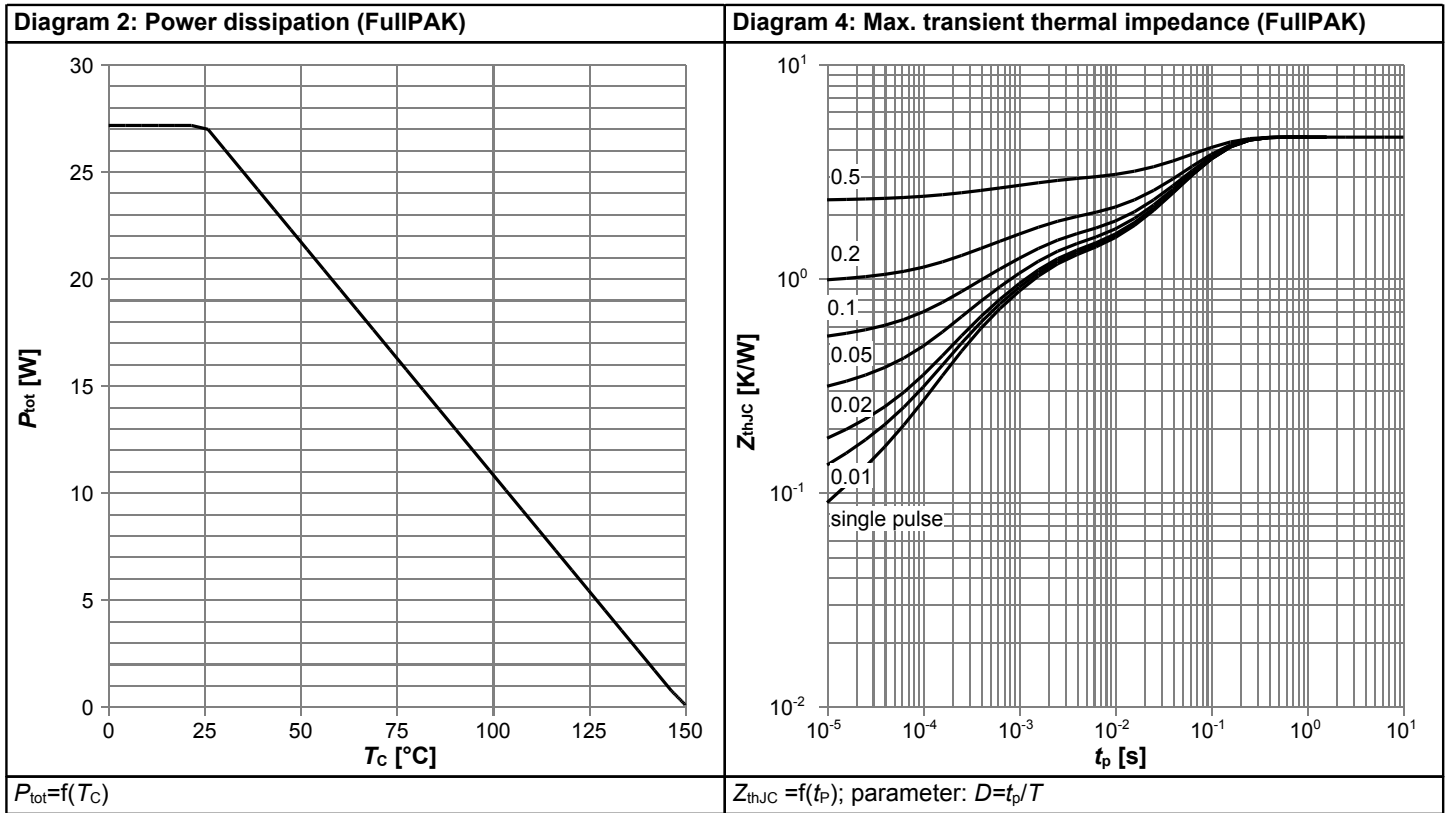
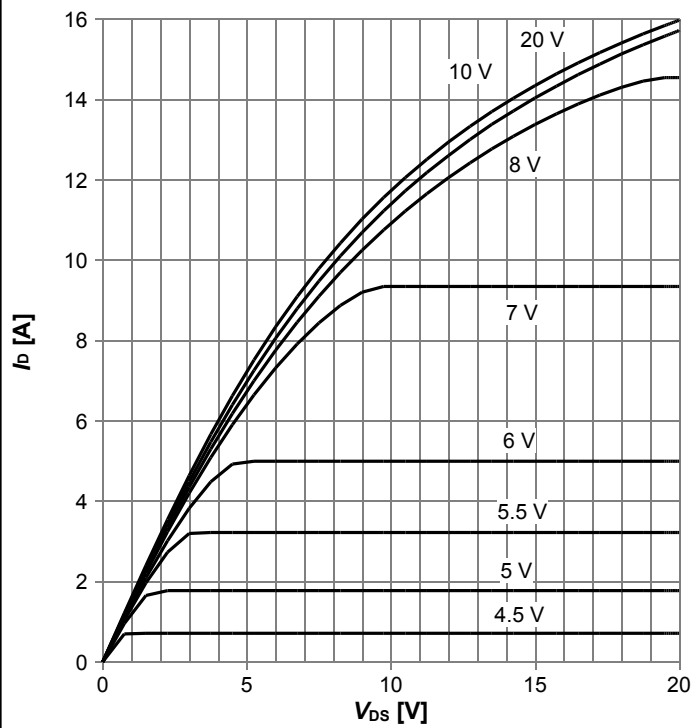
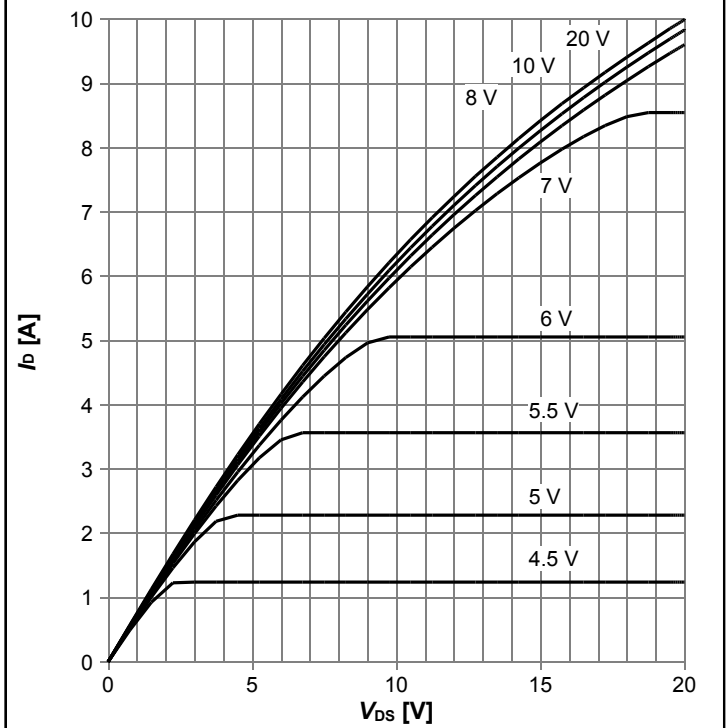


Diagram 9: Typ. output characteristics



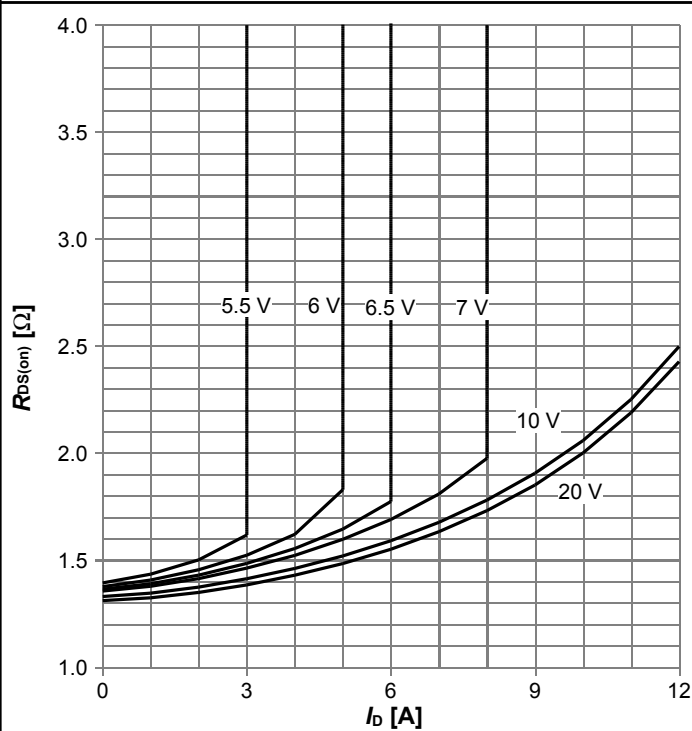
$I_D=f(V_{DS})$ ;  $T_j=25\text{ }^\circ\text{C}$ ; parameter:  $V_{GS}$

Diagram 10: Typ. output characteristics



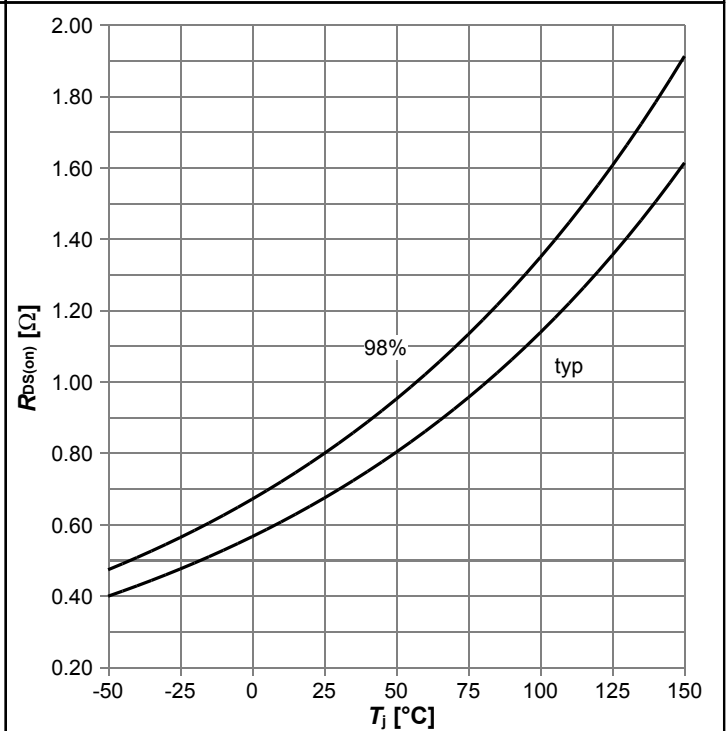
$I_D=f(V_{DS})$ ;  $T_j=125\text{ }^\circ\text{C}$ ; parameter:  $V_{GS}$

Diagram 11: Typ. drain-source on-state resistance



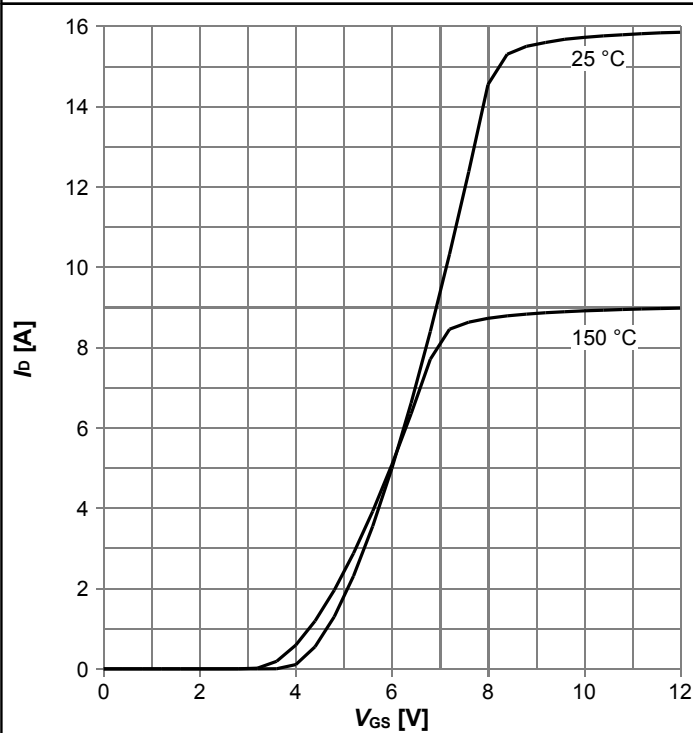
$R_{DS(on)}=f(I_D)$ ;  $T_j=125\text{ }^\circ\text{C}$ ; parameter:  $V_{GS}$

Diagram 12: Drain-source on-state resistance



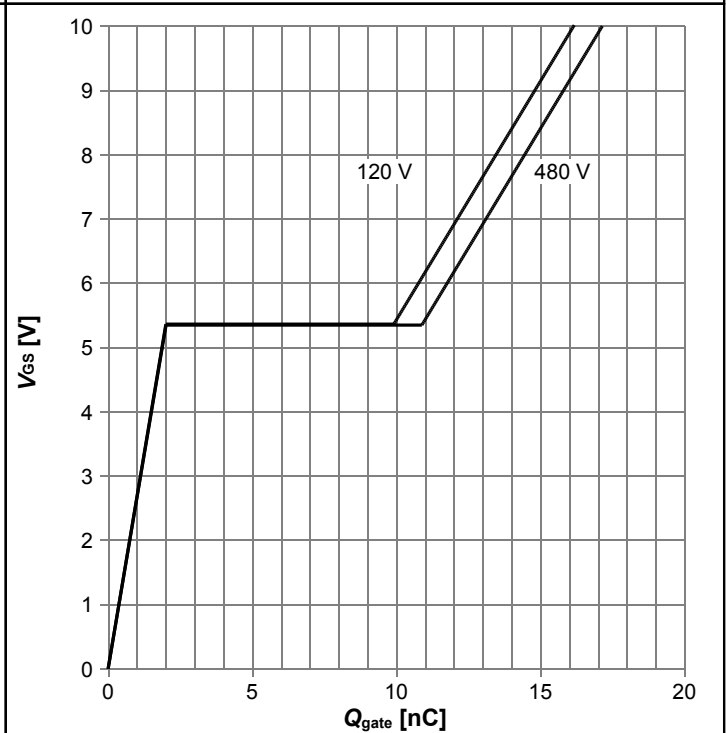
$R_{DS(on)}=f(T_j)$ ;  $I_D=2.0\text{ A}$ ;  $V_{GS}=10\text{ V}$

**Diagram 13: Typ. transfer characteristics**



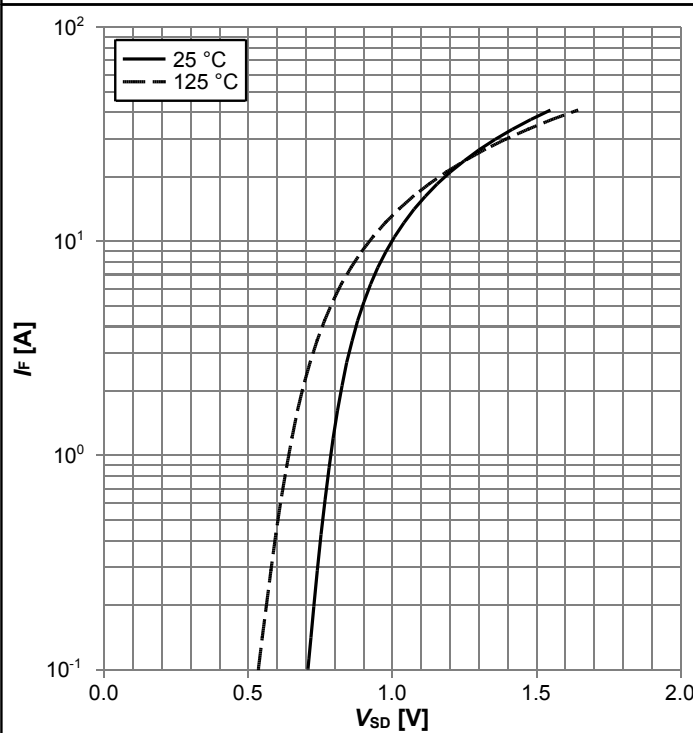
$I_D = f(V_{GS}); V_{DS} = 20V; \text{parameter: } T_j$

**Diagram 14: Typ. gate charge**



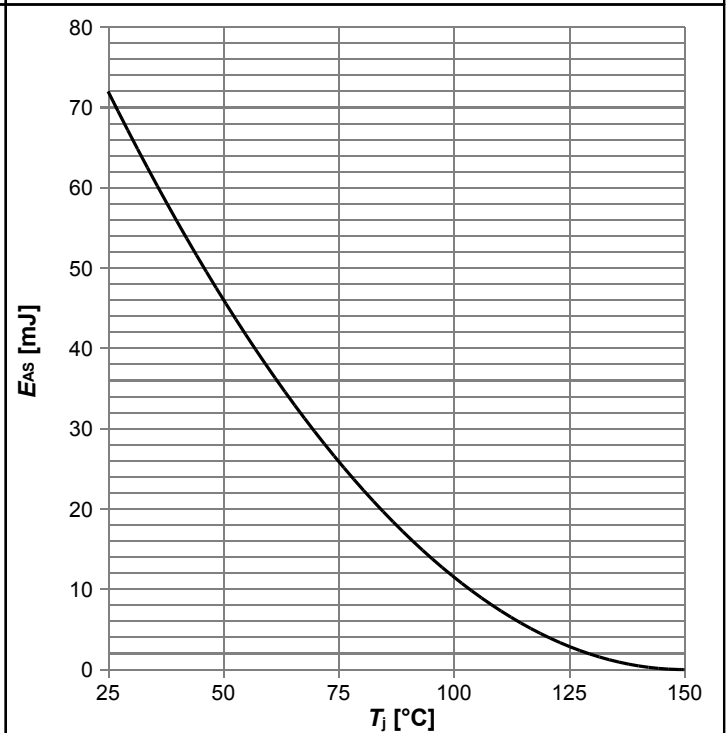
$V_{GS} = f(Q_{gate}); I_D = 2.5 \text{ A pulsed}; \text{parameter: } V_{DD}$

**Diagram 15: Forward characteristics of reverse diode**



$I_F = f(V_{SD}); \text{parameter: } T_j$

**Diagram 16: Avalanche energy**

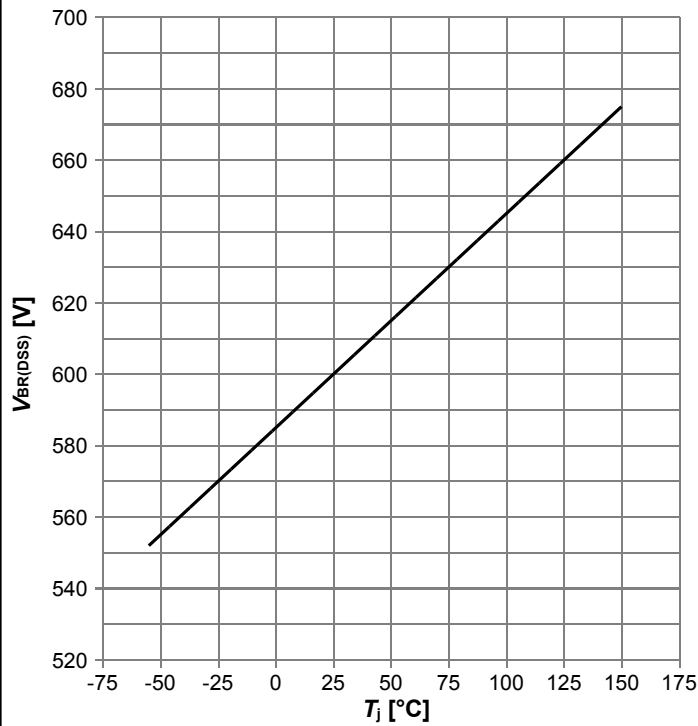


$E_{AS} = f(T_j); I_D = 1.0 \text{ A}; V_{DD} = 50 \text{ V}$

# 600V CoolMOS™ CE Power Transistor

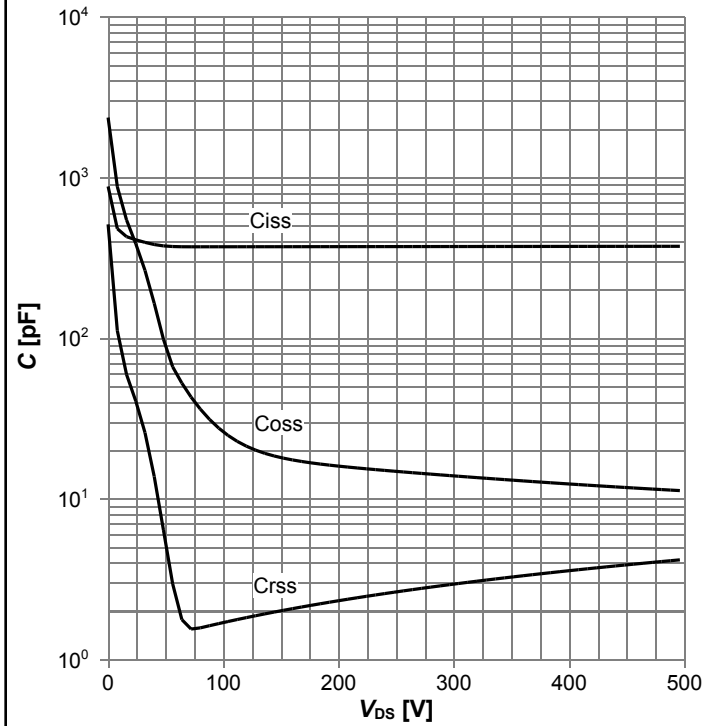
## IPAN60R800CE

**Diagram 17: Drain-source breakdown voltage**



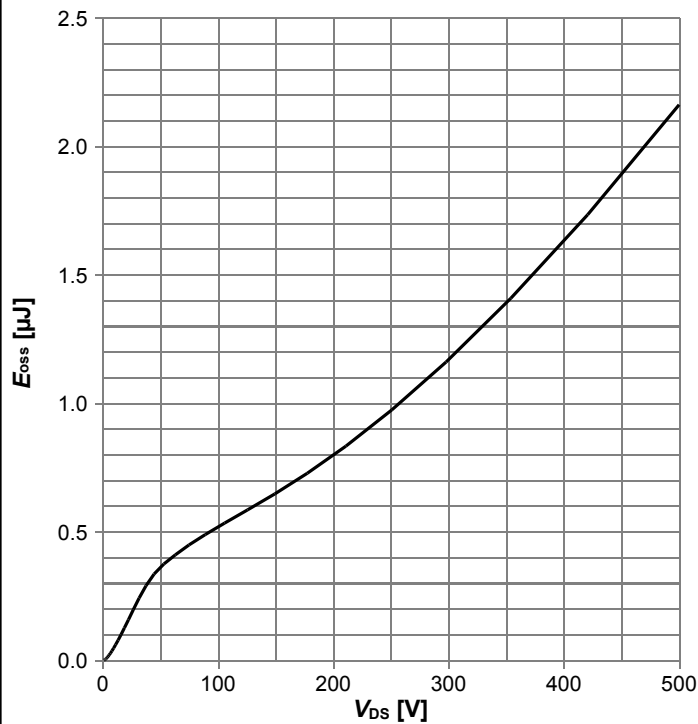
$V_{BR(DSS)}=f(T_j); I_D=0.25 \text{ mA}$

**Diagram 18: Typ. capacitances**



$C=f(V_{DS}); V_{GS}=0 \text{ V}; f=1 \text{ MHz}$

**Diagram 19: Typ. Coss stored energy**



$E_{oss}=f(V_{DS})$

## 5 Test Circuits

**Table 8 Diode characteristics**

Test circuit for diode characteristics	Diode recovery waveform

**Table 9 Switching times**

Switching times test circuit for inductive load	Switching times waveform

**Table 10 Unclamped inductive load**

Unclamped inductive load test circuit	Unclamped inductive waveform

**6 Package Outlines**

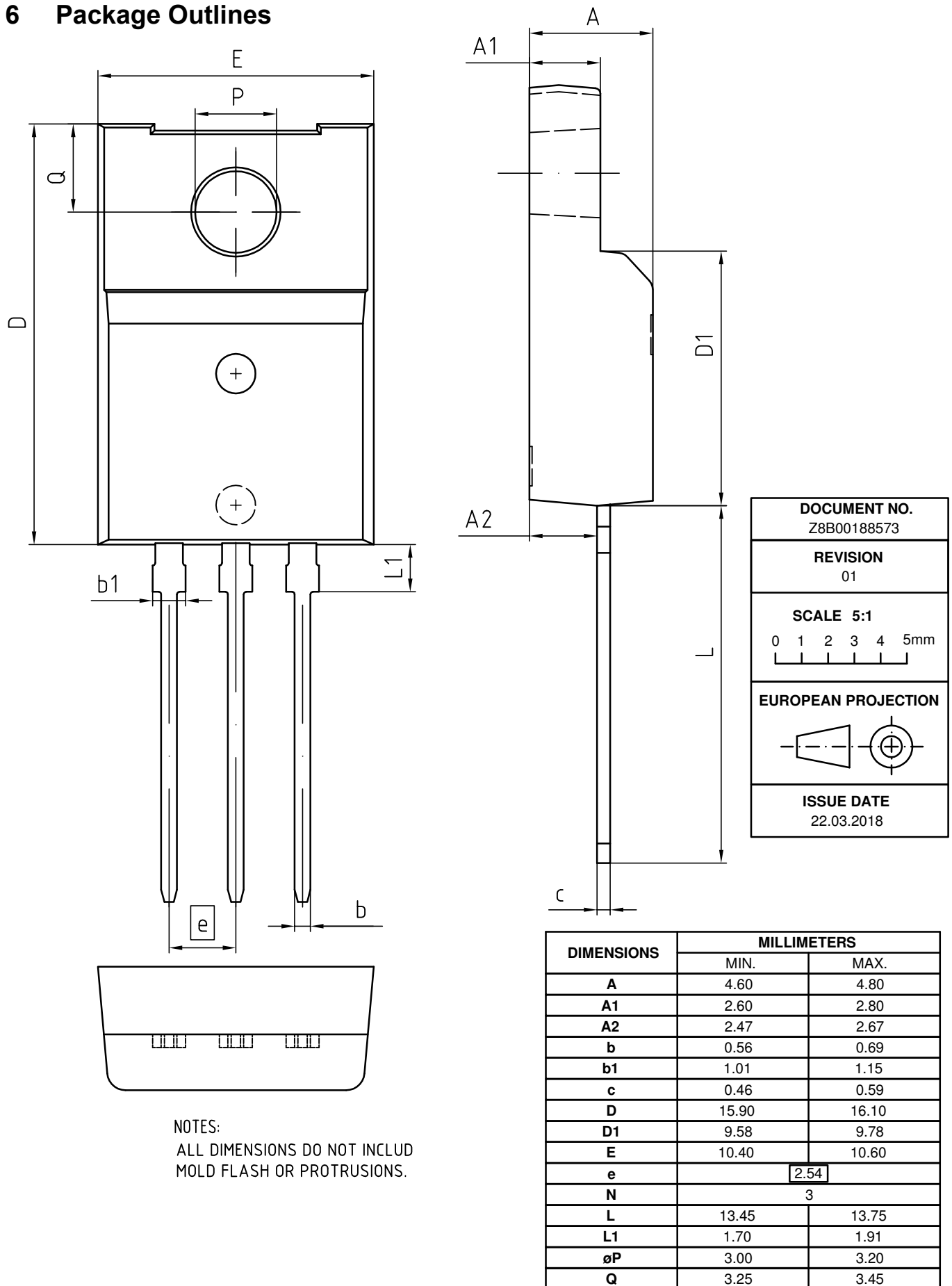


Figure 1 Outline PG-TO 220 FullPAK - Narrow Lead, dimensions in mm

## 7 Appendix A

Table 11 Related Links

- IFX CoolMOS™ CE Webpage: [www.infineon.com](http://www.infineon.com)
- IFX CoolMOS™ CE application note: [www.infineon.com](http://www.infineon.com)
- IFX CoolMOS™ CE simulation model: [www.infineon.com](http://www.infineon.com)
- IFX Design tools: [www.infineon.com](http://www.infineon.com)

## Revision History

IPAN60R800CE

**Revision: 2018-04-30, Rev. 2.2**

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.1	2016-11-28	Revised package drawing on page 11
2.2	2018-04-30	Revised package drawing

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